

Silicon N-Channel Power MOSFET

Description

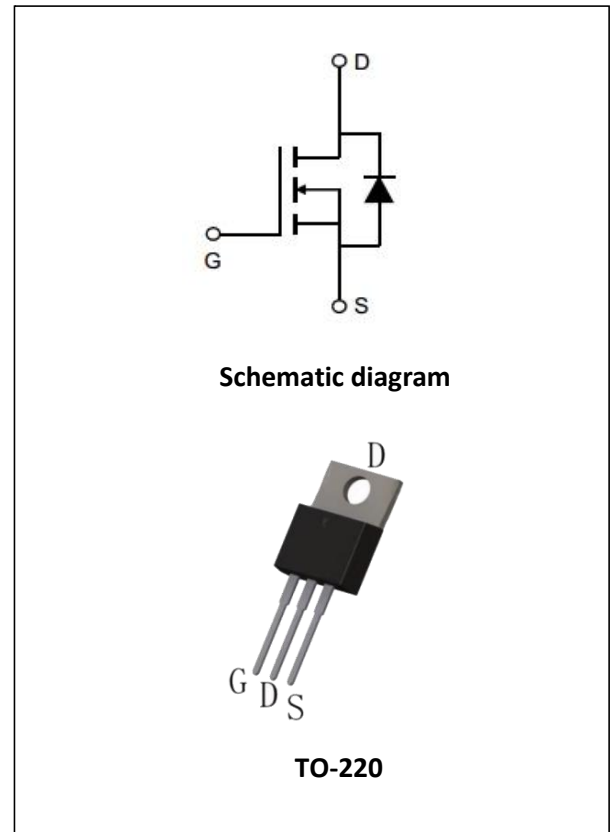
The MP50N06 uses advanced trench technology and design to provide Excellent $R_{DS(ON)}$. It can be used in a wide variety of applications.

General Features

- ① $V_{DS}=60V, I_D=50A$
 $R_{dson} \cong 14m\Omega @ V_{GS}=10V$ (Typ:11.0 m Ω)
 $R_{dson} \cong 16m\Omega @ V_{GS}=4.5V$ (Typ:12.5m Ω)
- ② Low ON Resistance
- ③ Low Reverse transfer capacitances
- ④ 100% Single Pulse avalanche energy Test

Application

- ① Power switching application
- ② Load switch



Package Marking And Ordering Information:

Ordering Codes	Package	Product Code	Packing
MP50N06	TO-220	MP50N06P	Tube

Electrical Characteristics @ Ta=25°C (unless otherwise specified)

Limited Parameters:

Symbol	Parameter	Value	Units
V_{DSS}	Drain-to-Source Breakdown Voltage	60	V
I_D	Drain Current (continuous) at Tc=25°C	50	A
I_{DM}	Drain Current (pulsed)	200	A
V_{GS}	Gate to Source Voltage	+/-20	V
P_{tot}	Total Dissipation at Tc=25°C	100	W
T_j	Max. Operating Junction Temperature	175	°C
Eas	Single Pulse Avalanche Energy	256	mj



Electrical Parameters:

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{DS}	Drain-source Voltage	$V_{GS}=0V, I_D=250\mu A$	60	66		V
$R_{DS(on)}$	Static Drain-to-Source on-Resistance	$V_{GS}=10V, I_D=25A$		11.0	14	m Ω
		$V_{GS}=4.5V, I_D=15A$		12.5	16	m Ω
$V_{GS(th)}$	Gated Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.9	2.5	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1.0	μA
$I_{GSS(F)}$	Gated Body Leakage Current	$V_{GS}=+20V,$			100	nA
$I_{GSS(R)}$	Gated Body Leakage Current	$V_{GS}=-20V,$			-100	nA
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=25V,$ $f=1.0MHz$		2200		pF
C_{oss}	Output Capacitance			225		pF
C_{rSS}	Reverse Transfer Capacitance			165		pF
Q_g	Total Gate Charge	$V_{DS}=25V$		58		nC
Q_{gs}	Gate-Source Charge	$I_D=10A$		6		nC
Q_{gd}	Gate-Drain Charge	$V_{GS}=10V$		15		nC

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=25V, I_D=10A, R_L=0.3\Omega$ $V_{GS}=10V, R_G=6.8\Omega$		20		nS
t_r	Turn-on Rise Time			90		nS
$t_{d(off)}$	Turn-off Delay Time			45		nS
t_f	Turn-off Fall Time			90		nS

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_{SD}	S-D Current(Body Diode)			50		A
I_{SDM}	Pulsed S-D Current(Body Diode)			200		A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_{DS}=25A$			1.4	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ C, I_F=25A$ $di/dt=100A/us$		102		nS
Q_{rr}	Reverse Recovery Charge			50		nC
*Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$						

Symbol	Parameter	Typ	Units
$R_{\theta JC}$	Junction-to-Case	1.3	$^\circ C/W$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

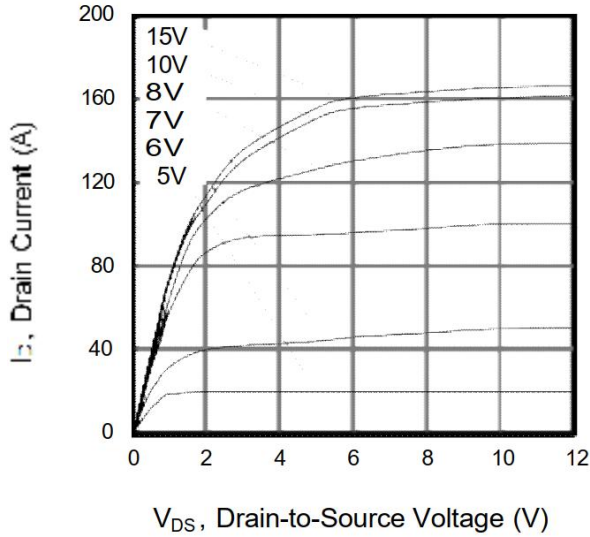


Figure 2. Body Diode Forward Voltage

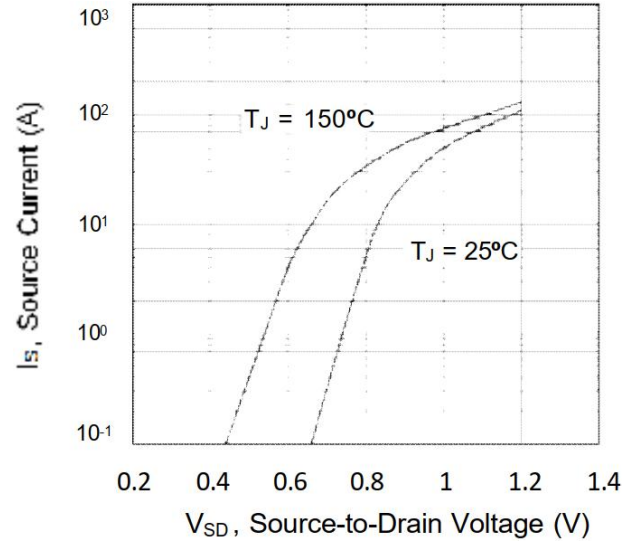


Figure 3. Drain Current vs. Temperature

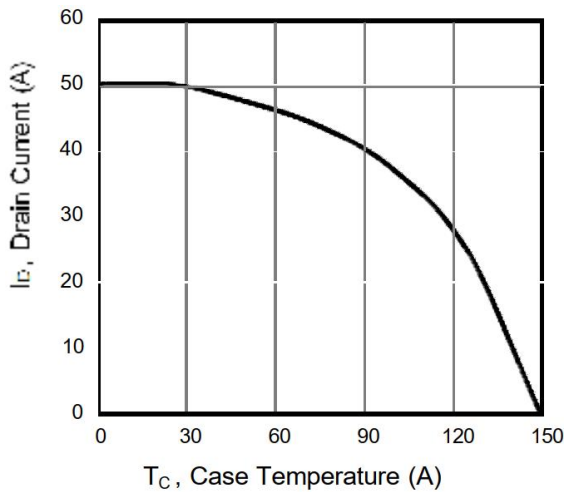


Figure 4. BV_{DSS} Variation vs. Temperature

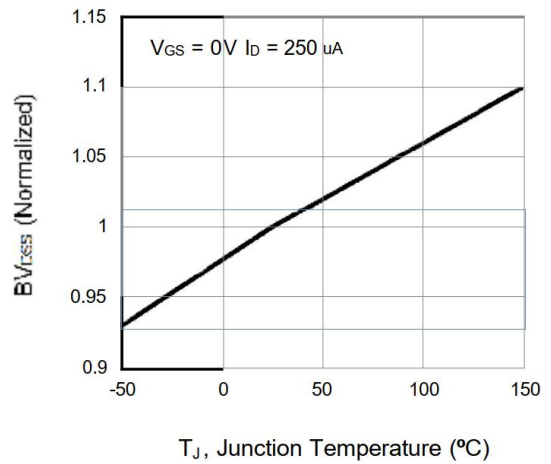


Figure 5. Transfer Characteristics

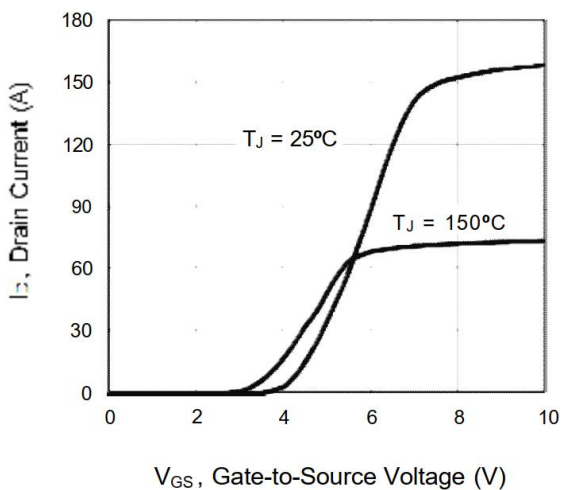
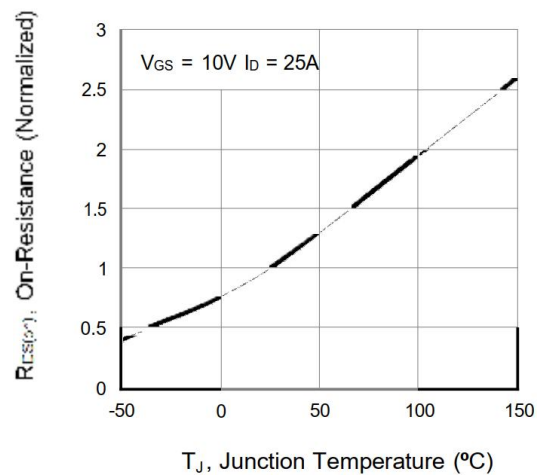


Figure 6. On-Resistance vs. Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Capacitance

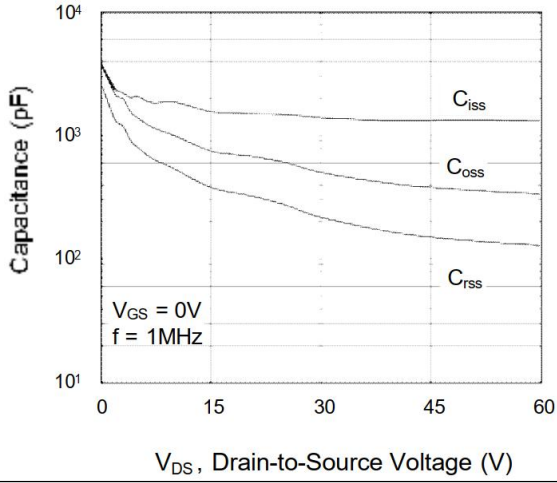


Figure 8. Gate Charge

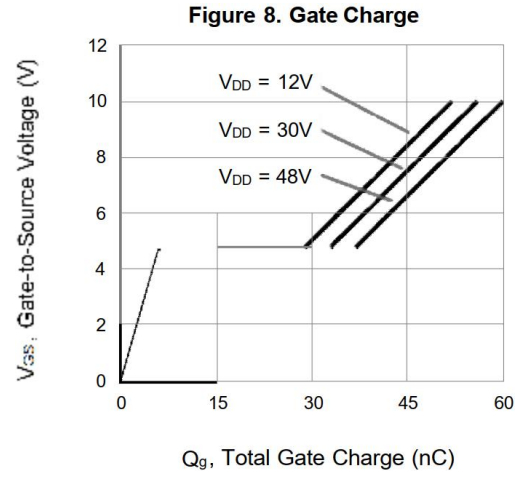


Figure 9. Transient Thermal Impedance

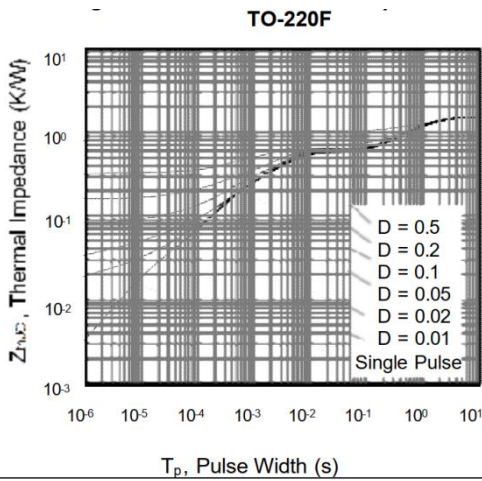


Figure 10. Transient Thermal Impedance

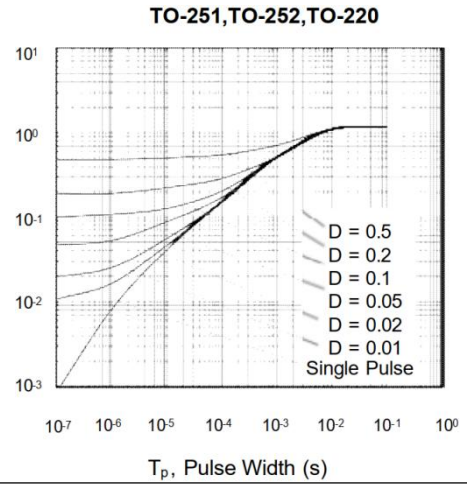


Figure A: Gate Charge Test Circuit and Waveform

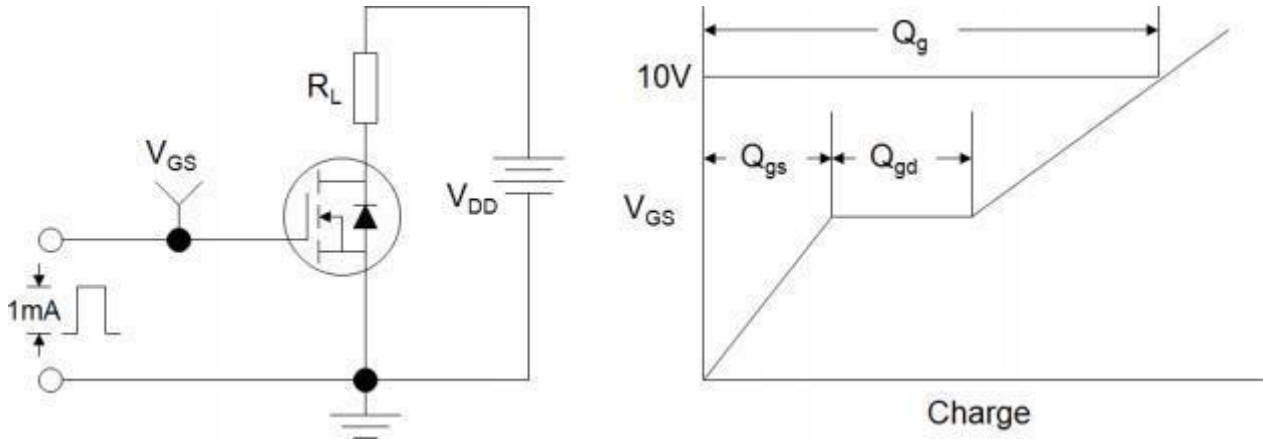


Figure B: Resistive Switching Test Circuit and Waveform

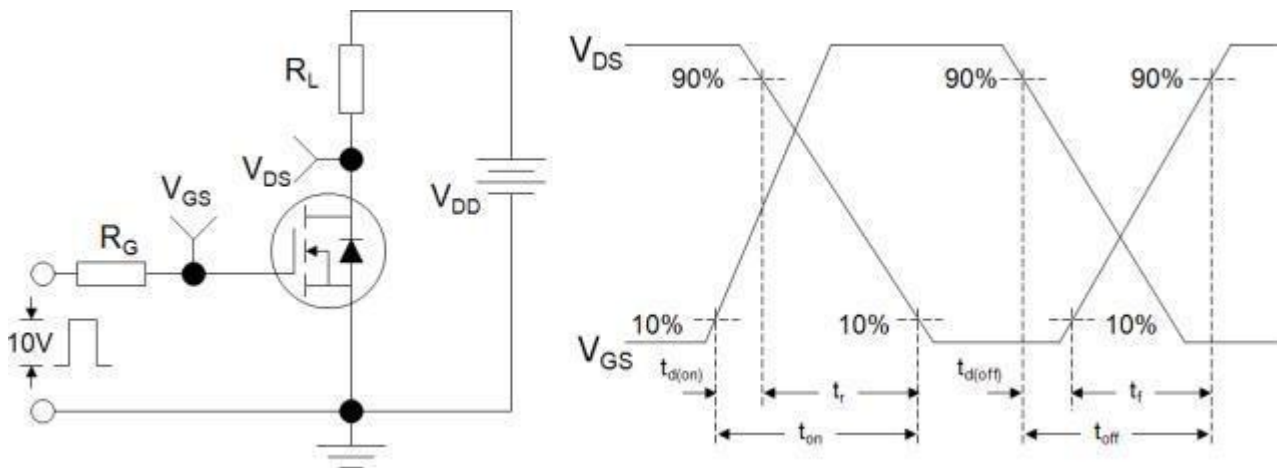
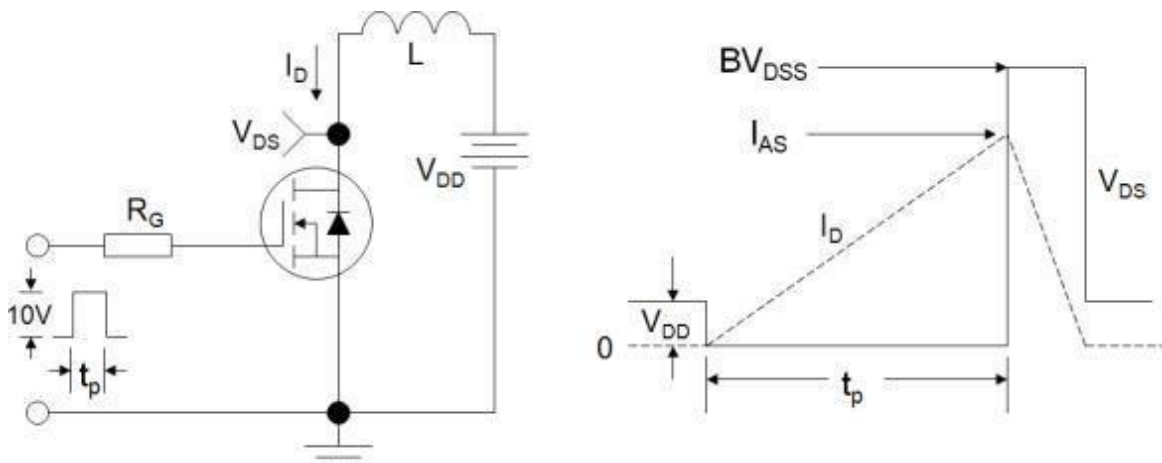


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shenzhen Minos reserves the right to make changes in this specification sheet and is subject to change without prior notice.

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